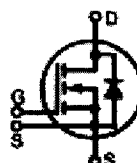


MegaMOS™FET

IXTN 79N20

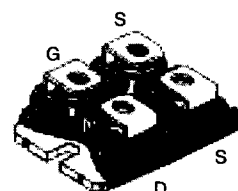
$$\begin{aligned} V_{DSS} &= 200 \text{ V} \\ I_{D25} &= 85 \text{ A} \\ R_{DS(on)} &= 25 \text{ m}\Omega \end{aligned}$$

N-Channel Enhancement Mode



Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ\text{C to } 150^\circ\text{C}$	200	V
V_{DGR}	$T_J = 25^\circ\text{C to } 150^\circ\text{C}; R_{GS} = 10 \text{ k}\Omega$	200	V
V_{GS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	$T_C = 25^\circ\text{C}$	85	A
I_{DM}	$T_C = 25^\circ\text{C}$, pulse width limited by T_{JM}	340	A
P_D	$T_C = 25^\circ\text{C}$	400	W
T_J		-40 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		-40 ... +150	$^\circ\text{C}$
V_{ISOL}	50/60 Hz	t = 1 min	2500 V~
	$I_{ISOL} \leq 1 \text{ mA}$	t = 1 s	3000 V~
M_d	Mounting torque	1.5/13	Nm/lb.in.
	Terminal connection torque (M4)	1.5/13	Nm/lb.in.
Weight		30	g

miniBLOC, SOT-227 B
E153432



G = Gate D = Drain
S = Source
Either Source terminal at miniBLOC can be used as Main or Kelvin Source

Features

- International standard package miniBLOC (ISOTOP compatible)
- Isolation voltage 3000 V~
- Low $R_{DS(on)}$ HDMOS™ process
- Rugged polysilicon gate cell structure
- Low drain-to-case capacitance (< 50 pF)
- Low package inductance (< 10 nH)
- easy to drive and to protect

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
V_{DSS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	200		V
$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 20 \text{ mA}$	2		5 V
I_{GSS}	$V_{GS} = \pm 20 \text{ V}_{DC}, V_{DS} = 0$			$\pm 500 \text{ nA}$
I_{DSS}	$V_{DS} = 0.8 \cdot V_{DSS}$			400 μA
	$V_{GS} = 0 \text{ V}$			2 mA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}, I_D = 0.5 \cdot I_{D25}$ Pulse test, t $\leq 300 \mu\text{s}$, duty cycle d $\leq 2 \%$			0.025 Ω

Applications

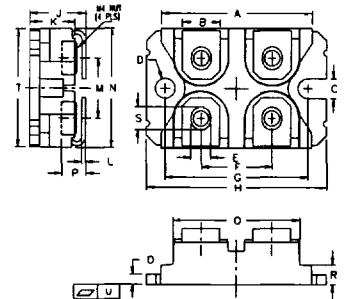
- AC motor speed control
- DC servo and robot drives
- Uninterruptible power systems (UPS)
- Switch-mode and resonant-mode power supplies
- DC choppers

Advantages

- Easy to mount with 2 screws
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
g_{fs}	$V_{DS} = 10\text{ V}; I_D = 0.5 \cdot I_{D25}, \text{ pulsed}$	44	58	S
C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		9000	pF
C_{oss}			1600	pF
C_{rss}			600	pF
$t_{d(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 I_{D25}$ $R_G = 1\ \Omega, \text{ (External)}$			70 ns
t_r				80 ns
$t_{d(off)}$				200 ns
t_f				100 ns
$Q_{g(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 I_{D25}$		380	450 nC
Q_{gs}			70	110 nC
Q_{gd}			190	230 nC
R_{thJC}				0.31 K/W
R_{thCK}			0.05	K/W

Source-Drain Diode		Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
Symbol	Test Conditions	min.	typ.	max.
I_S	$V_{GS} = 0\text{ V}$			85 A
I_{SM}	Repetitive; pulse width limited by T_{JM}			340 A
V_{SD}	$I_F = I_S, V_{GS} = 0\text{ V},$ Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $d \leq 2\%$			1.2 V
t_{rr}	$I_F = I_S, -di/dt = 100\text{ A}/\mu\text{s}, V_R = 100\text{ V}$		400	ns

miniBLOC, SOT-227 B


M4 screws (4x) supplied

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	31.5	31.7	1.241	1.249
B	7.8	8.2	0.307	0.323
C	4.0	-	0.158	-
D	4.1	4.3	0.162	0.169
E	4.1	4.3	0.162	0.169
F	14.9	15.1	0.587	0.595
G	30.1	30.3	1.186	1.193
H	38.0	38.2	1.497	1.505
J	11.8	12.2	0.465	0.481
K	8.9	9.7	0.351	0.382
L	0.75	0.85	0.030	0.033
M	12.6	12.8	0.496	0.504
N	25.2	25.4	0.993	1.001
O	1.95	2.05	0.077	0.081
P	-	5.0	-	0.197

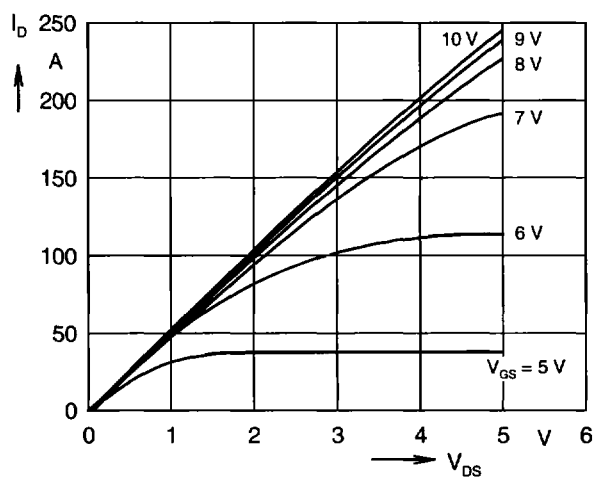


Fig. 1 Typical output characteristics $I_D = f(V_{DS})$

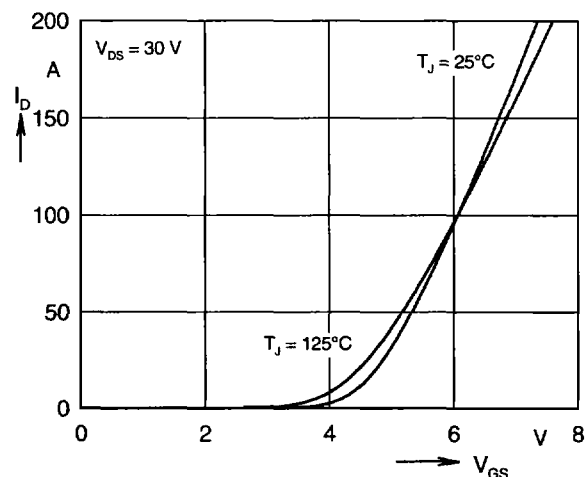


Fig. 2 Typical transfer characteristics $I_D = f(V_{GS})$

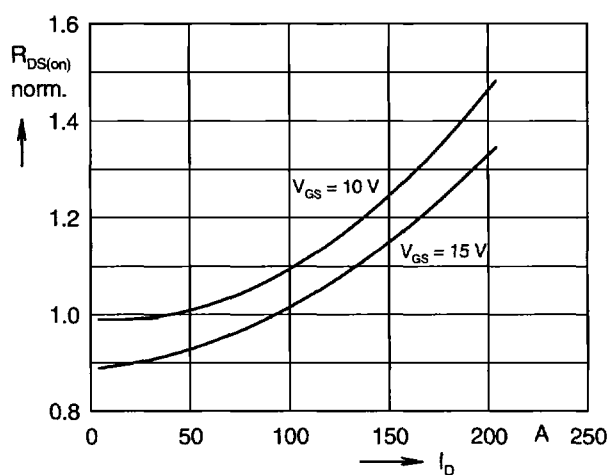


Fig. 3 Typical normalized $R_{DS(on)} = f(I_D)$

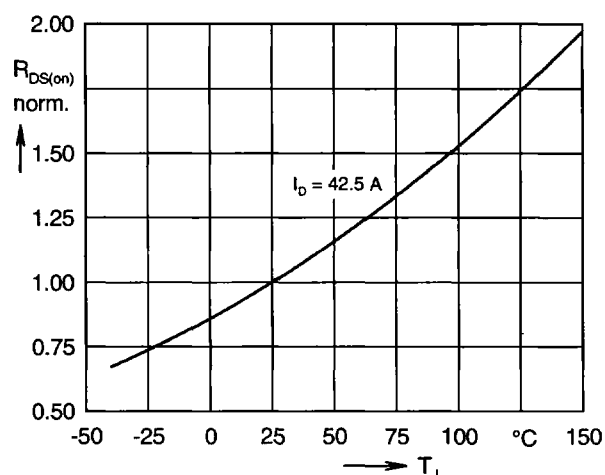


Fig. 4 Typical normalized $R_{DS(on)} = f(T_J)$

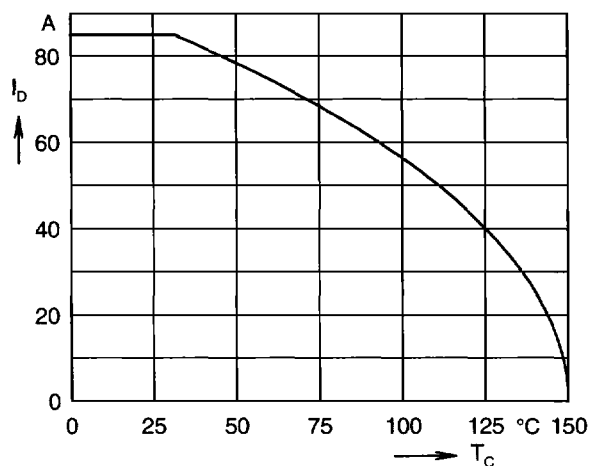


Fig. 5 Continuous drain current $I_D = f(T_C)$

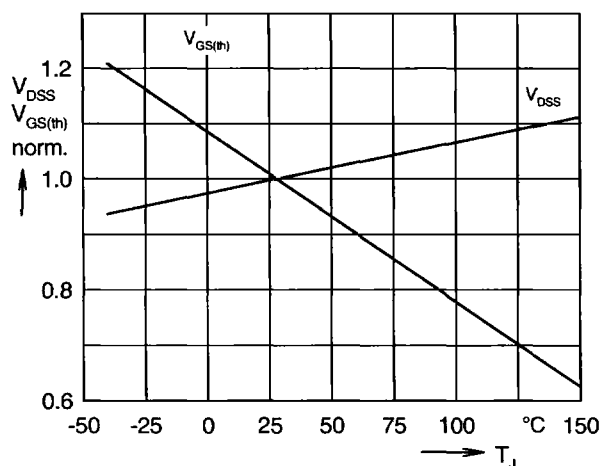


Fig. 6 Typical normalized $V_{DS} = f(T_J)$, $V_{GS(th)} = f(T_J)$

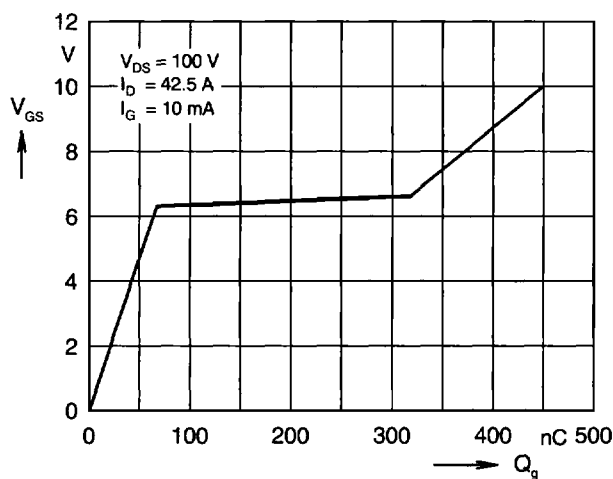


Fig. 7 Typical turn-on gate charge characteristics

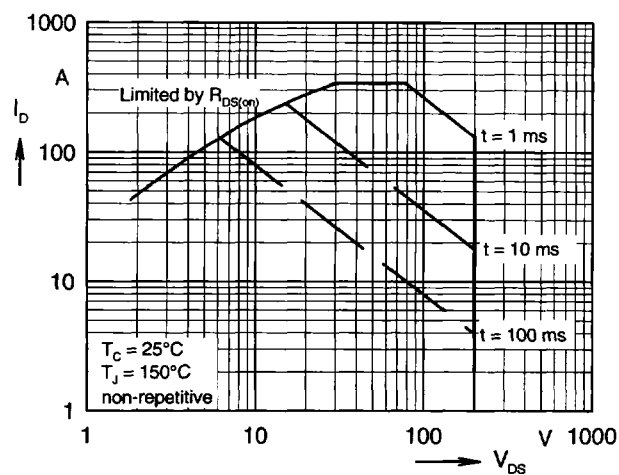


Fig. 8 Forward Safe Operating Area, $I_D = f(V_{DS})$

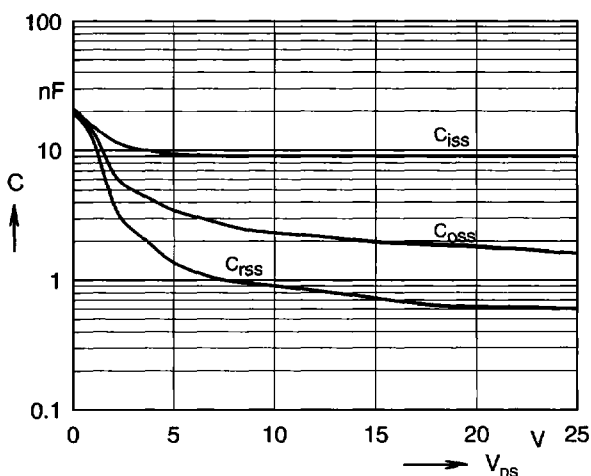


Fig. 9 Typical capacitances $C = f(V_{DS})$, $f = 1 \text{ MHz}$

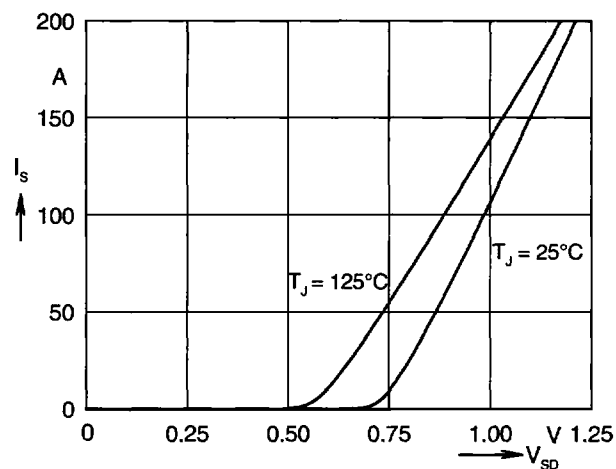


Fig. 10 Typical forward characteristics of reverse diode, $I_S = f(V_{SD})$

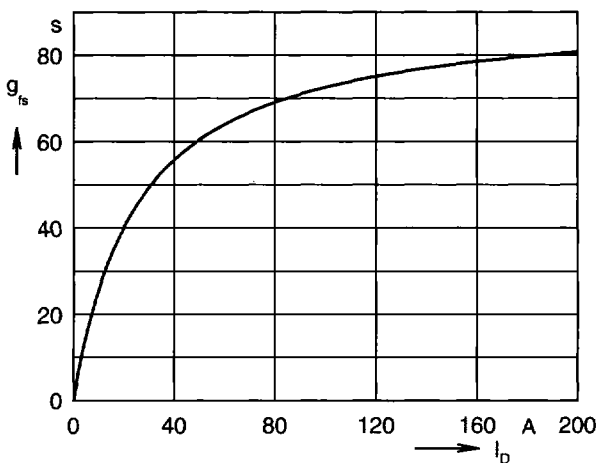


Fig. 11 Typical transconductance $g_{fs} = f(I_D)$

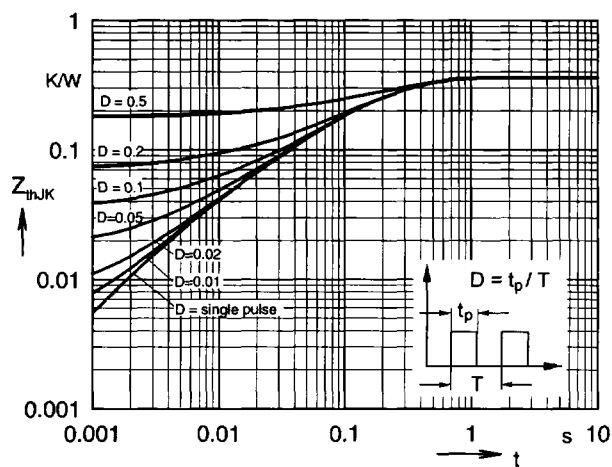


Fig. 12 Transient thermal resistance $Z_{thJK} = f(t_p)$